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THIN INTEGRATED CIRCUIT UNIT



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ABSTRACT OF THE DISCLOSURE

5 A high density unit (130, 160) comprising a first
integrated circuit package (30, 32) comprising a carrier (70)
having first and second sides (92, 94), a silicon chip (50)
attached by an adhesive layer (60) and solder bonding (80)
electrically connecting the silicon chip (50) to the carrier
10 (70) stackably and electrically connected to a second
integrated circuit package (30, 32), is disclosed.

15